













LM193, LM293, LM293A, LM393, LM393A, LM2903, LM2903V

SLCS005Z-OCTOBER 1979-REVISED OCTOBER 2017

LM393, LM293, LM193, LM2903 Dual Differential Comparators

Features

- Single-Supply or Dual Supplies
- Wide Range of Supply Voltage
 - Maximum Rating: 2 V to 36 V
 - Tested to 30 V: Non-V Devices
 - Tested to 32 V: V-Suffix Devices
- Low Supply-Current Drain Independent of Supply Voltage: 0.4 mA (Typical) Per Comparator
- Low Input Bias Current: 25 nA (Typical)
- Low Input Offset Current: 3 nA (Typical) (LM193)
- Low Input Offset Voltage: 2 mV (Typical)
- Common-Mode Input Voltage Range Includes Ground
- Differential Input Voltage Range Equal to Maximum-Rated Supply Voltage: ±36 V
- Low Output Saturation Voltage
- Output Compatible With TTL, MOS, and CMOS
- On Products Compliant to MIL-PRF-38535. All Parameters Are Tested Unless Otherwise Noted, On All Other Products, Production Processing Does Not Necessarily Include Testing of All Parameters.

Applications

- Chemical or Gas Sensor
- Desktop PC
- Motor Control: AC Induction
- Weigh Scale

3 Description

These devices consist of two independent voltage comparators that are designed to operate from a single power supply over a wide range of voltages. Operation from dual supplies also is possible as long as the difference between the two supplies is 2 V to 36 V, and V_{CC} is at least 1.5 V more positive than the input common-mode voltage. Current drain is independent of the supply voltage. The outputs can be connected to other open-collector outputs to achieve wired-AND relationships.

The LM193 device is characterized for operation from -55°C to +125°C. The LM293 and LM293A devices are characterized for operation from -25°C to +85°C. The LM393 and LM393A devices are characterized for operation from 0°C to 70°C. The LM2903, LM2903V, and LM2903AV devices are characterized for operation from -40°C to +125°C.

Device Information⁽¹⁾

Device illiorillation.								
PART NUMBER	PACKAGE	BODY SIZE (NOM)						
LM193D, LM293D, LM293AD, LM393D, LM393AD, LM2903D, LM2903QD, LM2903VQD, LM2903AVQD	SOIC (8)	4.90 mm x 6.00 mm						
LM293DGK, LM293ADGK, LM393DGK, LM393ADGK, LM2903DGK	VSSOP (8)	3.00 mm x 5.00 mm						
LM293P, LM393P, LM393AP, LM2903P	PDIP (8)	9.50 mm × 6.30 mm						
LM393PS, LM393APS, LM2903PS	SO (8)	6.20 mm x 7.90 mm						
LM393PW, LM393APW, LM2903PW, LM2903VQPW, LM2903AVQPW	TSSOP (8)	6.40 mm x 3.00 mm						
LM193JG	CDIP (8)	10.00 mm x 7.00 mm						
LM193FK	LCCC (20)	9.00 mm x 9.00 mm						

⁽¹⁾ For all available packages, see the orderable addendum at the end of the data sheet.

Simplified Schematic

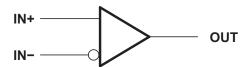




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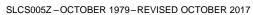
4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

CI	hanges from Revision Y (June 2015) to Revision Z	Page
•	Changed text from: LM139 to: LM193	1
•	Changed data sheet title	1
•	Added LM2903 part numbers	1
•	Added LM2903 part numbers	1
•	Changed VCC and ground pin function from: input to: –	
•	Changed T _J to T _A , split part numbers	
•	Changed 25C to -25C due to typo in LM293 Temperature Tablenote	6
•	Remove text "four comparators" from I _{CC}	7
•	Changed 25C to -25C due to typo in LM293 Temperature Tablenote	
•	Changed input error in Feature Description text	10
•	Changed Design Paramter maximum current from: 20 mA to: 4 mA	
•	Changed and revised text in Response Time section	12
•	Added Receiving Notification of Documentation Updates section	
CI	hanges from Revision X (January 2014) to Revision Y	Page
•	Added ESD Ratings table, Feature Description section, Device Functional Modes, Application and Implen	nentation

section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section.

LM193, LM293, LM293A, LM393, LM393A, LM2903, LM2903V





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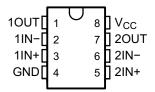
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•	Updated document to new TI data sheet format - no specification changes.	1
•	Updated Features	1
•	Removed Ordering Information table	3
•	Added ESD warning.	15

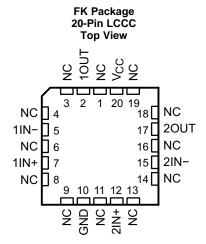
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5 Pin Configuration and Functions

D, DGK, JG, P, PS, or PW 8-Pin SOIC, VSSOP, CDIP, PDIP, SO, or TSSOP Top View





NC - No internal connection

Pin Functions

	PIN			T I directions
NAME	SOIC, VSSOP, CDIP, PDIP, SO, and TSSOP	LCCC	I/O	DESCRIPTION
1OUT	1	2	Output	Output pin of comparator 1
1IN-	2	5	Input	Negative input pin of comparator 1
1IN+	3	7	Input	Positive input pin of comparator 1
GND	4	10	_	Ground
2IN+	5	12	Input	Positive input pin of comparator 2
2IN-	6	15	Input	Negative input pin of comparator 2
2OUT	7	17	Output	Output pin of comparator 2
V _{CC}	8	20	_	Supply Pin
Vcc		3		
		4	ı	
		6		
		8		
NC		9	N/A	No Connect (No Internal Connection)
INC	_	11	IN/A	No Connect (No Internal Connection)
		13		
		14		
		16		
		18		
		19		



6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

			MIN	MAX	UNIT
V_{CC}	Supply voltage ⁽²⁾			36	V
V_{ID}	Differential input voltage (3)			±36	V
VI	Input voltage (either input)	-0.3	36	V	
I _{IK}	Input current ⁽⁴⁾	Input current ⁽⁴⁾			mA
Vo	Output voltage		36	V	
Io	Output current			20	mA
	Duration of output short circuit to ground (5)		Unlimit	ted	
T_{J}	Operating virtual-junction temperature			150	°C
	Case temperature for 60 s	FK package		260	°C
	Lead temperature 1.6 mm (1/16 in) from case for 60 s	JG package		300	°C
T _{stg}	Storage temperature		-65	150	°C

⁽¹⁾ Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- (2) All voltage values, except differential voltages, are with respect to network ground.
- 3) Differential voltages are at IN+ with respect to IN-.
- (4) Input current flows thorough parasitic diode to ground and will turn on parasitic transistors that will increase ICC and may cause output to be incorrect. Normal operation resumes when input current is removed.
- (5) Short circuits from outputs to V_{CC} can cause excessive heating and eventual destruction.

6.2 ESD Ratings

			VALUE	UNIT
V	Floatroototic disabores	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	1000	\/
V _(ESD)	Electrostatic discharge	Charged-device model (CDM), per JEDEC specification JESD22-C101 (2)	750	V

¹⁾ JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V _{CC}	Supply voltage	non-V devices	2	30	V
		V devices	2	32	V
	Operating temperature	LM193	-55	125	°C
		LM293, LM293A	-25	85	°C
T _A		LM393, LM393A	0	70	°C
		LM2903, LM2903V, LM2903AV	-40	125	°C

JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.



6.4 Thermal Information LM293, LM393, LM2903 (all suffixes)

	THERMAL METRIC ⁽¹⁾	D (SOIC)	DGK (VSSOP)	P (PDIP)	PS (SO)	PW (TSSOP)	UNIT
		8 PINS	8 PINS	8 PINS	8 PINS	8 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	131.8	199.4	73.7	139	194.1	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	78.4	90.2	62.6	98.9	77	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	72.2	120.8	50.8	83.7	123	°C/W
ΨЈТ	Junction-to-top characterization parameter	26.5	21.5	39.2	47.4	13.1	°C/W
ΨЈВ	Junction-to-board characterization parameter	71.7	119.1	50.7	83	121.3	°C/W

⁽¹⁾ For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.

6.5 Thermal Information LM193

		LM193			
THERMAL METRIC ⁽¹⁾		JG (GDIP)	FK (LCCC)	UNIT	
		8 PINS	20 PINS		
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	14.5	5.61	°C/W	

For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.



6.6 Electrical Characteristics for LM193, LM293, and LM393 (without A suffix)

at specified free-air temperature, V_{CC} = 5 V (unless otherwise noted)

	PARAMETER	TEST CONDITIONS		T _A ⁽¹⁾	T _A ⁽¹⁾			LM: LM:			UNIT
				,	MIN	TYP	MAX	MIN	TYP	MAX	
		$V_{CC} = 5 \text{ V to } 3$		25°C		2	5		2	5	
V _{IO}	Input offset voltage	$V_{IC} = V_{ICR} min$ $V_{O} = 1.4 V$,	Full range			9			9	mV
	Innut offeet current	V 1.4.V		25°C		3	25		5	50	Λ
I _{IO}	Input offset current	V _O = 1.4 V		Full range			100			250	nA
	Innut higo guerant	V 1.4.V		25°C		-25	-100		-25	-250	Λ
I _{IB}	Input bias current	V _O = 1.4 V		Full range			-300			-400	nA
	Common-mode input-voltage range (2)			25°C	0 to V _{CC} - 1.5			0 to V _{CC} - 1.5			
V _{ICR}				Full range	0 to V _{CC} - 2			0 to V _{CC} - 2			V
A _{VD}	Large-signal differential-voltage amplification	$V_{CC} = 15 \text{ V},$ $V_{O} = 1.4 \text{ V to}$ $R_{L} \ge 15 \text{ k}\Omega \text{ to}$		25°C	50	200		50	200		V/mV
	High level output ourrent	V _{OH} = 5 V	V _{ID} = 1 V	25°C		0.1			0.1	50	nA
I _{OH}	High-level output current	$V_{OH} = 30 \text{ V}$	$V_{ID} = 1 V$	Full range			1			1	μΑ
\/	Low lovel output voltage	l - 4 mΛ	\/ _ 1\/	25°C		150	400		130	400	mV
V_{OL}	Low-level output voltage	$I_{OL} = 4 \text{ mA},$	$V_{ID} = -1 V$	Full range			700			700	IIIV
I _{OL}	Low-level output current	V _{OL} = 1.5 V,	V _{ID} = −1 V	25°C	6			6			mA
	Supply ourrant	D - m	$V_{CC} = 5 V$	25°C		8.0	1		0.45	1	mA
I _{CC}	Supply current	R _L = ∞	V _{CC} = 30 V	Full range			2.5		0.55	2.5	IIIA

⁽¹⁾ Full range (minimum or maximum) for LM193 is -55°C to 125°C, for LM293 is -25°C to 85°C, and for LM393 is 0°C to 70°C. All characteristics are measured with zero common-mode input voltage, unless otherwise specified.

⁽²⁾ The voltage at either input should not be allowed to go negative by more than 0.3 V otherwise output may be incorrect and excessive input current can flow. The upper end of the common-mode voltage range is limited by V_{CC} – 2V. However only one input needs to be in the valid common mode range, the other input can go up the maximum V_{CC} level and the comparator provides a proper output state. Either or both inputs can go to maximum V_{CC} level without damage.



6.7 Electrical Characteristics for LM293A and LM393A

at specified free-air temperature, V_{CC} = 5 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T _A ⁽¹⁾	LM29 LM39	UNIT		
					MIN	TYP	MAX	
V	Input offset voltage	V _{CC} = 5 V to 30 V, V	/ _O = 1.4 V	25°C		1	2	mV
V _{IO}	input onset voitage	$V_{IC} = V_{ICR(min)}$		Full range			4	IIIV
	Input offset current	V - 1.4.V		25°C		5	50	nA
I _{IO}	Input offset current	V _O = 1.4 V		Full range			150	nA
	Input bigg gurrant	V _O = 1.4 V		25°C		-25	-250	nA
I _{IB}	Input bias current	V _O = 1.4 V		Full range			-400	IIA
V	Common mode input valtege range (2)	nmon-mode input-voltage range ⁽²⁾		25°C	$V_{CC} - 1.5$			٧
V _{ICR}	Common-mode input-voltage range			Full range	$\begin{array}{c} 0 \text{ to} \\ V_{CC} - 2 \end{array}$			V
A _{VD}	Large-signal differential-voltage amplification	$V_{CC} = 15 \text{ V}, V_{O} = 1.4 \text{ R}_{L} \ge 15 \text{ k}\Omega \text{ to } V_{CC}$	4 V to 11.4 V,	25°C	50	200		V/mV
	High-level output current	V _{OH} = 5 V,	$V_{ID} = 1 V$	25°C		0.1	50	nA
I _{OH}	High-level output current	V _{OH} = 30 V,	$V_{ID} = 1 V$	Full range			1	μΑ
V	Low-level output voltage	l - 4 mΔ	V - 1 V	25°C		110	400	mV
V _{OL}	Low-level output voltage	$I_{OL} = 4 \text{ mA},$	$V_{ID} = -1 V$	Full range		-	700	IIIV
I_{OL}	Low-level output current	V _{OL} = 1.5 V,	$V_{ID} = -1 V$,	25°C	6			mA
	Supply current	D	$V_{CC} = 5 V$	25°C		0.60	1	mA
I _{CC}	Supply current	R _L = ∞	V _{CC} = 30 V	Full range		0.72	2.5	IIIA

⁽¹⁾ Full range (minimum or maximum) for LM293A is -25°C to 85°C, and for LM393A is 0°C to 70°C. All characteristics are measured with zero common-mode input voltage, unless otherwise specified.

⁽²⁾ The voltage at either input should not be allowed to go negative by more than 0.3 V otherwise output may be incorrect and excessive input current can flow. The upper end of the common-mode voltage range is limited by V_{CC} – 2V. However only one input needs to be in the valid common mode range, the other input can go up the maximum V_{CC} level and the comparator provides a proper output state. Either or both inputs can go to maximum V_{CC} level without damage.



6.8 Electrical Characteristics for LM2903, LM2903V, and LM2903AV

at specified free-air temperature, $V_{CC} = 5 \text{ V}$ (unless otherwise noted)

	DADAMETED	TEST COM	DITIONS	T (1)	LM2903,	LM290	3V	LM29	03AV		UNIT
	PARAMETER	TEST CON	DITIONS	T _A ⁽¹⁾	MIN	TYP	MAX	MIN	TYP	MAX	UNII
		$V_{CC} = 5 \text{ V to MAX}^{(2)}$,		25°C		2	7		1	2	
V _{IO}	Input offset voltage	$V_O = 1.4 \text{ V},$ $V_{IC} = V_{ICR(min)},$		Full range			15			4	mV
	Input offset current	V _O = 1.4 V		25°C		5	50		5	50	nA
I _{IO}	input onset current	V _O = 1.4 V		Full range			200			200	IIA
	Input bias current	V _O = 1.4 V		25°C		-25	-250		-25	-250	nA
I _{IB}	input bias current	V _O = 1.4 V		Full range			-500			-500	IIA
.,	Common-mode input-			25°C	0 to V _{CC} -1.5			0 to V _{CC} - 1.5			
V _{ICR}	voltage range ⁽³⁾			Full range	0 to V _{CC} - 2			0 to V _{CC} - 2			V
A _{VD}	Large-signal differential- voltage amplification	$V_{CC} = 15 \text{ V}, V_{O} = 1.4 \text{ V}$ $R_{L} \ge 15 \text{ k}\Omega \text{ to } V_{CC}$	V to 11.4 V,	25°C	25	100		25	100		V/mV
	High-level output current	V _{OH} = 5 V,	$V_{ID} = 1 V$	25°C		0.1	50		0.1	50	nA
I _{OH}	nigh-level output current	$V_{OH} = V_{CC} MAX^{(2)},$	$V_{ID} = 1 V$	Full range			1			1	μΑ
.,	Low lovel output voltoge	Ι 4 200 Δ	V 4.V	25°C		150	400		150	400	mV
V_{OL}	Low-level output voltage	$I_{OL} = 4 \text{ mA},$	$V_{ID} = -1 V$,	Full range			700			700	IIIV
I _{OL}	Low-level output current	V _{OL} = 1.5 V,	V _{ID} = -1 V	25°C	6			6			mA
	0	D	V _{CC} = 5 V	25°C		0.8	1		0.8	1	^
I _{CC}	Supply current	R _L = ∞	V _{CC} = MAX	Full range			2.5			2.5	mA

⁽¹⁾ Full range (minimum or maximum) for LM2903 is -40°C to 125°C. All characteristics are measured with zero common-mode input voltage, unless otherwise specified.

6.9 Switching Characteristics (all devices)

 $V_{CC} = 5 \text{ V}, T_A = 25^{\circ}\text{C}$

PARAMETER	TEST COND	ITIONS	TYP	UNIT
Despense time	TY COMMICCICA to 5 V timoagn 5.1 K22,	100-mV input step with 5-mV overdrive	1.3	
Response time	$C_L = 15 \text{ pF}^{(1)(2)}$	TTL-level input step	0.3	μs

⁽¹⁾ C_L includes probe and jig capacitance.

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⁽²⁾ V_{CC} MAX = 30 V for non-V devices and 32 V for V-suffix devices.

⁽³⁾ The voltage at either input should not be allowed to go negative by more than 0.3 V otherwise output may be incorrect and excessive input current can flow. The upper end of the common-mode voltage range is limited by V_{CC} – 2V. However only one input needs to be in the valid common mode range, the other input can go up the maximum V_{CC} level and the comparator provides a proper output state. Either or both inputs can go to maximum V_{CC} level without damage.

⁽²⁾ The response time specified is the interval between the input step function and the instant when the output crosses 1.4 V.



6.10 Typical Characteristics

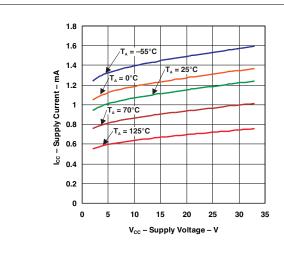


Figure 1. Supply Current vs Supply Voltage

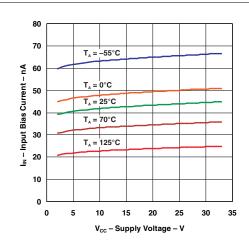


Figure 2. Input Bias Current vs Supply Voltage

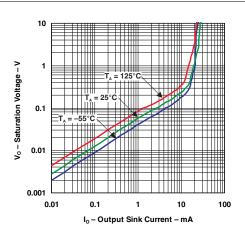


Figure 3. Output Saturation Voltage

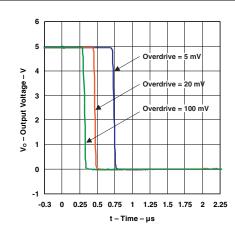


Figure 4. Response Time for Various Overdrives

Negative Transition

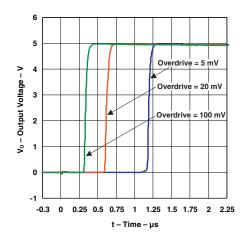


Figure 5. Response Time for Various Overdrives
Positive Transition



7 Detailed Description

7.1 Overview

These dual comparators have the ability to operate up to absolute maximum of 36 V on the supply pin. This device has proven ubiquity and versatility across a wide range of applications. This is due to very wide supply voltages range (2 V to 36 V), low Iq and fast response of the devices.

The open-drain output allows the user to configure the output's logic high voltage (V_{OH}) and can be used to enable the comparator to be used in AND functionality.

7.2 Functional Block Diagram

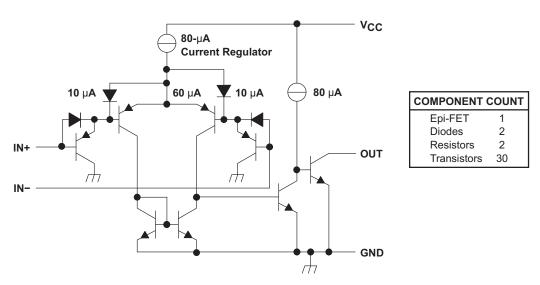


Figure 6. Schematic (Each Comparator)

7.3 Feature Description

The comparator consists of a PNP darlington pair input, allowing the device to operate with very high gain and fast response with minimal input bias current. The input Darlington pair creates a limit on the input common mode voltage capability, allowing the comparator to accurately function from ground to V_{CC} – 1.5 V input. Allow for V_{CC} – 2 V at cold temperature.

The output consists of an open drain NPN (pull-down or low side) transistor. The output NPN will sink current when the negative input voltage is higher than the positive input voltage and the offset voltage. The VOL is resistive and will scale with the output current. See Figure 3 for V_{OL} values with respect to the output current.

7.4 Device Functional Modes

7.4.1 Voltage Comparison

The device operates solely as a voltage comparator, comparing the differential voltage between the positive and negative pins and outputting a logic low or high impedance (logic high with pullup) based on the input differential polarity.



8 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

The device will typically be used to compare a single signal to a reference or two signals against each other. Many users take advantage of the open drain output to drive the comparison logic output to a logic voltage level to an MCU or logic device. The wide supply range and high voltage capability makes this comaprator optimal for level shifting to a higher or lower voltage.

8.2 Typical Application

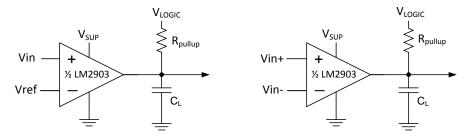


Figure 7. Single-Ended and Differential Comparator Configurations

8.2.1 Design Requirements

For this design example, use the parameters listed in Table 1 as the input parameters.

DESIGN PARAMETER EXAMPLE VALUE Input Voltage Range 0 V to Vsup-2 V Supply Voltage 4.5 V to V_{CC} maximum Logic Supply Voltage 0 V to V_{CC} maximum Output Current (R_{PULLUP}) $1 \mu A$ to 4 mAInput Overdrive Voltage 100 mV 2.5 V Reference Voltage Load Capacitance (C_I) 15 pF

Table 1. Design Parameters

8.2.2 Detailed Design Procedure

When using the device in a general comparator application, determine the following:

- Input Voltage Range
- Minimum Overdrive Voltage
- Output and Drive Current
- Response Time

8.2.2.1 Input Voltage Range

When choosing the input voltage range, the input common mode voltage range (V_{ICR}) must be taken in to account. If temperature operation is below 25°C the V_{ICR} can range from 0 V to V_{CC} – 2.0 V. This limits the input voltage range to as high as V_{CC} – 2.0 V and as low as 0 V. Operation outside of this range can yield incorrect comparisons.



The following is a list of input voltage situation and their outcomes:

- 1. When both IN- and IN+ are both within the common-mode range:
 - a. If IN- is higher than IN+ and the offset voltage, the output is low and the output transistor is sinking current
 - b. If IN- is lower than IN+ and the offset voltage, the output is high impedance and the output transistor is not conducting
- 2. When IN- is higher than common-mode and IN+ is within common-mode, the output is low and the output transistor is sinking current
- 3. When IN+ is higher than common-mode and IN- is within common-mode, the output is high impedance and the output transistor is not conducting
- 4. When IN- and IN+ are both higher than common-mode, the output is low and the output transistor is sinking current

8.2.2.2 Minimum Overdrive Voltage

Overdrive Voltage is the differential voltage produced between the positive and negative inputs of the comparator over the offset voltage (V_{IO}) . To make an accurate comparison the Overdrive Voltage (V_{OD}) should be higher than the input offset voltage (V_{IO}) . Overdrive voltage can also determine the response time of the comparator, with the response time decreasing with increasing overdrive. Figure 8 and Figure 9 show positive and negative response times with respect to overdrive voltage.

8.2.2.3 Output and Drive Current

Output current is determined by the load/pull-up resistance and logic/pullup voltage. The output current will produce a output low voltage (V_{OL}) from the comparator. In which V_{OL} is proportional to the output current. Use *Typical Characteristics* to determine V_{OL} based on the output current.

The output current can also effect the transient response. See *Response Time* for more information.

8.2.2.4 Response Time

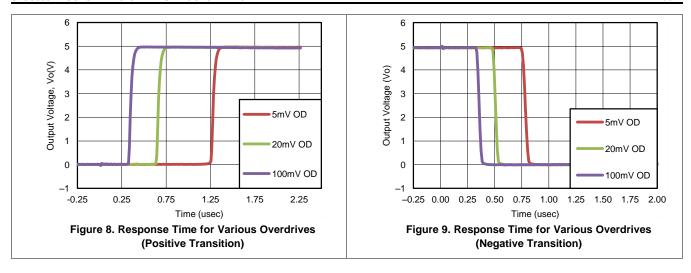
Response time is a function of input over drive. See *Application Curves* for typical response times. The rise and falls times can be determined by the load capacitance (C_L) , load/pullup resistance (R_{PULLUP}) and equivalent collector-emitter resistance (R_{CF}) .

- The rise time (τ_R) is approximately $\tau_R \sim R_{PULLUP} \times C_L$
- The fall time (τ_F) is approximately τ_F ~ R_{CE} × C_L
 - R_{CE} can be determine by taking the slope of *Typical Characteristics* in its linear region at the desired temperature, or by dividing the V_{OL} by I_{out}

8.2.3 Application Curves

The following curves were generated with 5 V on V_{CC} and V_{Logic} , $R_{PULLUP} = 5.1 \text{ k}\Omega$, and 50 pF scope probe.







9 Power Supply Recommendations

For fast response and comparison applications with noisy or AC inputs, TI recommends to use a bypass capacitor on the supply pin to reject any variation on the supply voltage. This variation can eat into the input common-mode range of the comparator and create an inaccurate comparison.

10 Layout

10.1 Layout Guidelines

For accurate comparator applications without hysteresis it is important maintain a stable power supply with minimized noise and glitches. To achieve this, it is best to add a bypass capacitor between the supply voltage and ground. This should be implemented on the positive power supply and negative supply (if available). If a negative supply is not being used, do not put a capacitor between the IC's GND pin and system ground.

Minimize coupling between outputs and inverting inputs to prevent output oscillations. Do not run output and inverting input traces in parallel unless there is a V_{CC} or GND trace between output and inverting input traces to reduce coupling. When series resistance is added to inputs, place resistor close to the device.

10.2 Layout Example

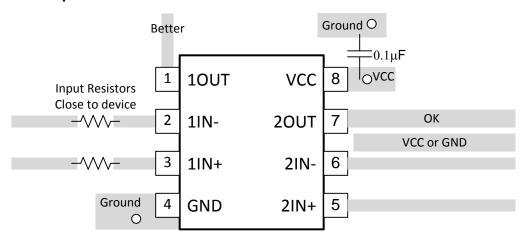


Figure 10. LM2903 Layout Example



11 Device and Documentation Support

11.1 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to order now.

Table 2. Related Links

PARTS	PRODUCT FOLDER	ORDER NOW	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
LM193	Click here	Click here	Click here	Click here	Click here
LM293	Click here	Click here	Click here	Click here	Click here
LM293A	Click here	Click here	Click here	Click here	Click here
LM393	Click here	Click here	Click here	Click here	Click here
LM393A	Click here	Click here	Click here	Click here	Click here
LM2903	Click here	Click here	Click here	Click here	Click here
LM2903V	Click here	Click here	Click here	Click here	Click here

11.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on Alert me to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

11.3 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

TI E2E™ Online Community TI's Engineer-to-Engineer (E2E) Community. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support TI's Design Support Quickly find helpful E2E forums along with design support tools and contact information for technical support.

11.4 Trademarks

E2E is a trademark of Texas Instruments.

All other trademarks are the property of their respective owners.

11.5 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

11.6 Glossary

SLYZ022 — TI Glossary.

This glossary lists and explains terms, acronyms, and definitions.

12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser based versions of this data sheet, refer to the left hand navigation.

Submit Documentation Feedback





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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Sample
LM193DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	LM193	Sample
LM193DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	LM193	Sample
LM2903AVQDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2903AV	Sample
LM2903AVQDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2903AV	Sample
LM2903AVQPWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2903AV	Sample
LM2903AVQPWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2903AV	Sample
LM2903D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2903	Sample
LM2903DE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2903	Sample
LM2903DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2903	Sample
LM2903DGKR	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU CU NIPDAUAG	Level-1-260C-UNLIM	-40 to 125	(MAP, MAS, MAU)	Sample
LM2903DGKRG4	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-1-260C-UNLIM	-40 to 125	(MAP, MAS, MAU)	Sample
LM2903DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM	-40 to 125	LM2903	Sample
LM2903DRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2903	Sample
LM2903DRG3	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	LM2903	Sample
LM2903DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2903	Sample
LM2903P	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	-40 to 125	LM2903P	Sample
LM2903PSR	ACTIVE	so	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2903	Sample



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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
LM2903PSRG4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2903	Samples
LM2903PWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM	-40 to 125	L2903	Samples
LM2903PWRG3	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	L2903	Samples
LM2903PWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2903	Sample
LM2903QD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2903Q	Sample
LM2903QDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2903Q	Samples
LM2903QDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2903Q	Sample
LM2903VQDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2903V	Sample
LM2903VQDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2903V	Sample
LM2903VQPWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2903V	Sample
LM2903VQPWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2903V	Sample
LM293AD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM293A	Sample
LM293ADE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM293A	Sample
LM293ADGKR	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU CU NIPDAUAG	Level-1-260C-UNLIM	-25 to 85	(MDP, MDS, MDU)	Sample
LM293ADGKRG4	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-1-260C-UNLIM	-25 to 85	(MDP, MDS, MDU)	Sample
LM293ADR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM	-25 to 85	LM293A	Sample
LM293ADRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM293A	Sample
LM293D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM293	Sample





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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
LM293DGKR	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU CU NIPDAUAG	Level-1-260C-UNLIM	-25 to 85	(MCP, MCS, MCU)	Samples
LM293DGKRG4	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-1-260C-UNLIM	-25 to 85	(MCP, MCS, MCU)	Samples
LM293DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM	-25 to 85	LM293	Samples
LM293DRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM293	Samples
LM293DRG3	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-25 to 85	LM293	Samples
LM293DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM293	Samples
LM293P	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	N / A for Pkg Type	-25 to 85	LM293P	Samples
LM293PE4	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	-25 to 85	LM293P	Samples
LM393AD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM393A	Samples
LM393ADE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM393A	Samples
LM393ADG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM393A	Samples
LM393ADGKR	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU CU NIPDAUAG	Level-1-260C-UNLIM	0 to 70	(M8P, M8S, M8U)	Samples
LM393ADGKRG4	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-1-260C-UNLIM	0 to 70	(M8P, M8S, M8U)	Samples
LM393ADR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM	0 to 70	LM393A	Samples
LM393ADRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM393A	Samples
LM393ADRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM393A	Samples
LM393AP	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	N / A for Pkg Type	0 to 70	LM393AP	Samples
LM393APE4	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	LM393AP	Samples



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Orderable Device	Status	Package Type	U	Pins	_	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
LM393APSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L393A	Sample
LM393APWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM	0 to 70	L393A	Sample
LM393APWRE4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L393A	Sample
LM393APWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L393A	Sample
LM393D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM393	Sample
LM393DE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM393	Samples
LM393DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM393	Samples
LM393DGKR	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU CU NIPDAUAG	Level-1-260C-UNLIM	0 to 70	(M9P, M9S, M9U)	Samples
LM393DGKRG4	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-1-260C-UNLIM	0 to 70	(M9P, M9S, M9U)	Samples
LM393DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM	0 to 70	LM393	Samples
LM393DRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM393	Samples
LM393DRG3	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	LM393	Samples
LM393DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM393	Samples
LM393P	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	N / A for Pkg Type	0 to 70	LM393P	Samples
LM393PE3	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 70	LM393P	Samples
LM393PE4	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	LM393P	Samples
LM393PSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L393	Samples
LM393PSRG4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L393	Sample



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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
LM393PW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L393	Samples
LM393PWG4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L393	Samples
LM393PWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM	0 to 70	L393	Samples
LM393PWRG3	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	L393	Samples
LM393PWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L393	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF LM2903, LM293:

Automotive: LM2903-Q1

● Enhanced Product: LM293-EP

NOTE: Qualified Version Definitions:

- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product Supports Defense, Aerospace and Medical Applications

PACKAGE MATERIALS INFORMATION

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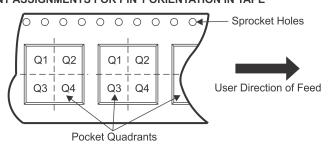
TAPE AND REEL INFORMATION





	Α0	Dimension designed to accommodate the component width
	B0	Dimension designed to accommodate the component length
	K0	Dimension designed to accommodate the component thickness
	W	Overall width of the carrier tape
г	D1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM193DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM2903AVQDR	SOIC	D	8	2500	330.0	12.5	6.4	5.2	2.1	8.0	12.0	Q1
LM2903AVQPWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
LM2903AVQPWRG4	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
LM2903DGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
LM2903DR	SOIC	D	8	2500	330.0	12.8	6.4	5.2	2.1	8.0	12.0	Q1
LM2903DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM2903DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM2903DRG3	SOIC	D	8	2500	330.0	12.8	6.4	5.2	2.1	8.0	12.0	Q1
LM2903DRG4	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM2903DRG4	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM2903PSR	SO	PS	8	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
LM2903PWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
LM2903PWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
LM2903PWRG3	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
LM2903PWRG4	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
LM2903QDRG4	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM2903VQDR	SOIC	D	8	2500	330.0	12.5	6.4	5.2	2.1	8.0	12.0	Q1



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Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM2903VQPWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
LM2903VQPWRG4	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
LM293ADGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
LM293ADR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM293ADR	SOIC	D	8	2500	330.0	12.8	6.4	5.2	2.1	8.0	12.0	Q1
LM293ADR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM293ADRG4	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM293ADRG4	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM293DGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
LM293DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM293DR	SOIC	D	8	2500	330.0	12.8	6.4	5.2	2.1	8.0	12.0	Q1
LM293DRG3	SOIC	D	8	2500	330.0	12.8	6.4	5.2	2.1	8.0	12.0	Q1
LM293DRG4	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM293DRG4	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM393ADGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
LM393ADR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM393ADR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM393ADR	SOIC	D	8	2500	330.0	12.8	6.4	5.2	2.1	8.0	12.0	Q1
LM393ADRG4	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM393ADRG4	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM393APSR	SO	PS	8	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
LM393APWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
LM393APWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
LM393APWRG4	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
LM393DGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
LM393DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM393DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM393DRG3	SOIC	D	8	2500	330.0	15.4	6.4	5.2	2.1	8.0	12.0	Q1
LM393DRG3	SOIC	D	8	2500	330.0	12.8	6.4	5.2	2.1	8.0	12.0	Q1
LM393DRG4	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM393DRG4	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM393PSR	SO	PS	8	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
LM393PWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
LM393PWRG3	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
LM393PWRG4	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM193DR	SOIC	D	8	2500	367.0	367.0	38.0
LM2903AVQDR	SOIC	D	8	2500	340.5	338.1	20.6
LM2903AVQPWR	TSSOP	PW	8	2000	367.0	367.0	35.0
LM2903AVQPWRG4	TSSOP	PW	8	2000	367.0	367.0	35.0
LM2903DGKR	VSSOP	DGK	8	2500	364.0	364.0	27.0
LM2903DR	SOIC	D	8	2500	364.0	364.0	27.0
LM2903DR	SOIC	D	8	2500	340.5	338.1	20.6
LM2903DR	SOIC	D	8	2500	367.0	367.0	35.0
LM2903DRG3	SOIC	D	8	2500	364.0	364.0	27.0
LM2903DRG4	SOIC	D	8	2500	340.5	338.1	20.6
LM2903DRG4	SOIC	D	8	2500	367.0	367.0	35.0
LM2903PSR	SO	PS	8	2000	367.0	367.0	38.0
LM2903PWR	TSSOP	PW	8	2000	367.0	367.0	35.0
LM2903PWR	TSSOP	PW	8	2000	364.0	364.0	27.0
LM2903PWRG3	TSSOP	PW	8	2000	364.0	364.0	27.0
LM2903PWRG4	TSSOP	PW	8	2000	367.0	367.0	35.0
LM2903QDRG4	SOIC	D	8	2500	367.0	367.0	38.0
LM2903VQDR	SOIC	D	8	2500	340.5	338.1	20.6
LM2903VQPWR	TSSOP	PW	8	2000	367.0	367.0	35.0
LM2903VQPWRG4	TSSOP	PW	8	2000	367.0	367.0	35.0



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Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM293ADGKR	VSSOP	DGK	8	2500	364.0	364.0	27.0
LM293ADR	SOIC	D	8	2500	340.5	338.1	20.6
LM293ADR	SOIC	D	8	2500	364.0	364.0	27.0
LM293ADR	SOIC	D	8	2500	367.0	367.0	35.0
LM293ADRG4	SOIC	D	8	2500	367.0	367.0	35.0
LM293ADRG4	SOIC	D	8	2500	340.5	338.1	20.6
LM293DGKR	VSSOP	DGK	8	2500	364.0	364.0	27.0
LM293DR	SOIC	D	8	2500	367.0	367.0	35.0
LM293DR	SOIC	D	8	2500	364.0	364.0	27.0
LM293DRG3	SOIC	D	8	2500	364.0	364.0	27.0
LM293DRG4	SOIC	D	8	2500	367.0	367.0	35.0
LM293DRG4	SOIC	D	8	2500	340.5	338.1	20.6
LM393ADGKR	VSSOP	DGK	8	2500	364.0	364.0	27.0
LM393ADR	SOIC	D	8	2500	367.0	367.0	35.0
LM393ADR	SOIC	D	8	2500	340.5	338.1	20.6
LM393ADR	SOIC	D	8	2500	364.0	364.0	27.0
LM393ADRG4	SOIC	D	8	2500	340.5	338.1	20.6
LM393ADRG4	SOIC	D	8	2500	367.0	367.0	35.0
LM393APSR	SO	PS	8	2000	367.0	367.0	38.0
LM393APWR	TSSOP	PW	8	2000	367.0	367.0	35.0
LM393APWR	TSSOP	PW	8	2000	364.0	364.0	27.0
LM393APWRG4	TSSOP	PW	8	2000	367.0	367.0	35.0
LM393DGKR	VSSOP	DGK	8	2500	364.0	364.0	27.0
LM393DR	SOIC	D	8	2500	367.0	367.0	35.0
LM393DR	SOIC	D	8	2500	340.5	338.1	20.6
LM393DRG3	SOIC	D	8	2500	333.2	345.9	28.6
LM393DRG3	SOIC	D	8	2500	364.0	364.0	27.0
LM393DRG4	SOIC	D	8	2500	340.5	338.1	20.6
LM393DRG4	SOIC	D	8	2500	367.0	367.0	35.0
LM393PSR	SO	PS	8	2000	367.0	367.0	38.0
LM393PWR	TSSOP	PW	8	2000	364.0	364.0	27.0
LM393PWRG3	TSSOP	PW	8	2000	364.0	364.0	27.0
LM393PWRG4	TSSOP	PW	8	2000	367.0	367.0	35.0

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.



D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.





NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



PS (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001 variation BA.



DGK (S-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 per end.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.50 per side.
- E. Falls within JEDEC MO-187 variation AA, except interlead flash.



DGK (S-PDSO-G8)

PLASTIC SMALL OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.





SMALL OUTLINE PACKAGE



- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153, variation AA.



SMALL OUTLINE PACKAGE



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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